SMD Power Inductors
-YSPI090840 Series

■ Features

- Molding Inductor.
- Low Profile,Low Temp.
- Large Current(Over 15A).
- Customize For Different Need.
- Operating temperature:-55℃ ~ +125℃.

■ Applications

- General Electronic.
- Video Device,TV,TFT.
- Power Module for PC.
- NB/Lap Top Computer.
- Server,VGA Card/Module.

■ Product Identification

YSPI □□□□□□□□ – □□□ □

(1) (2) (3) (4)

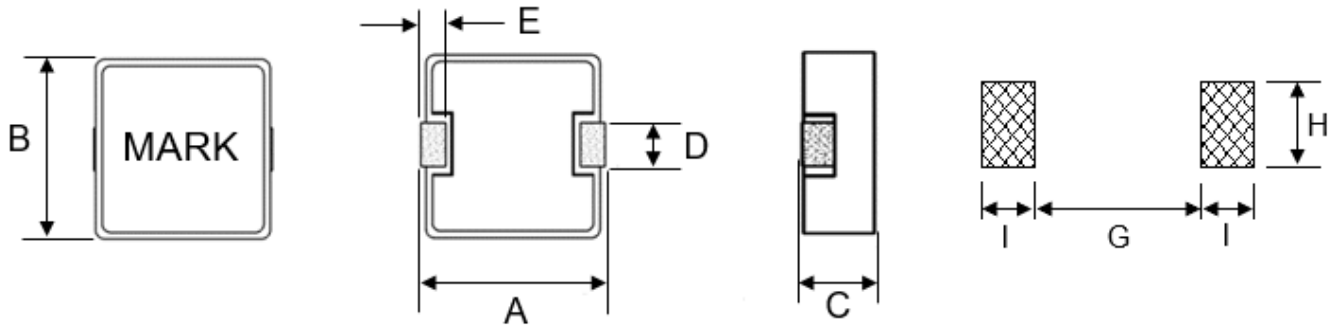
(1)： Type

(2)： Dimensions

(3)： Inductance value

(4)： Inductance Tolerance： N=±30%,M=±20%

■ Shapes and Dimensions (Unit： mm)



TYPE	A	B Max.	C Max.	D	E	G Ref.	H Ref.	I Ref.
YSPI090840	9.7±0.5	8.5	4.0	5.0±0.5	1.5±0.5	4.8	3.5	2.5

■ YSPI090840 Series

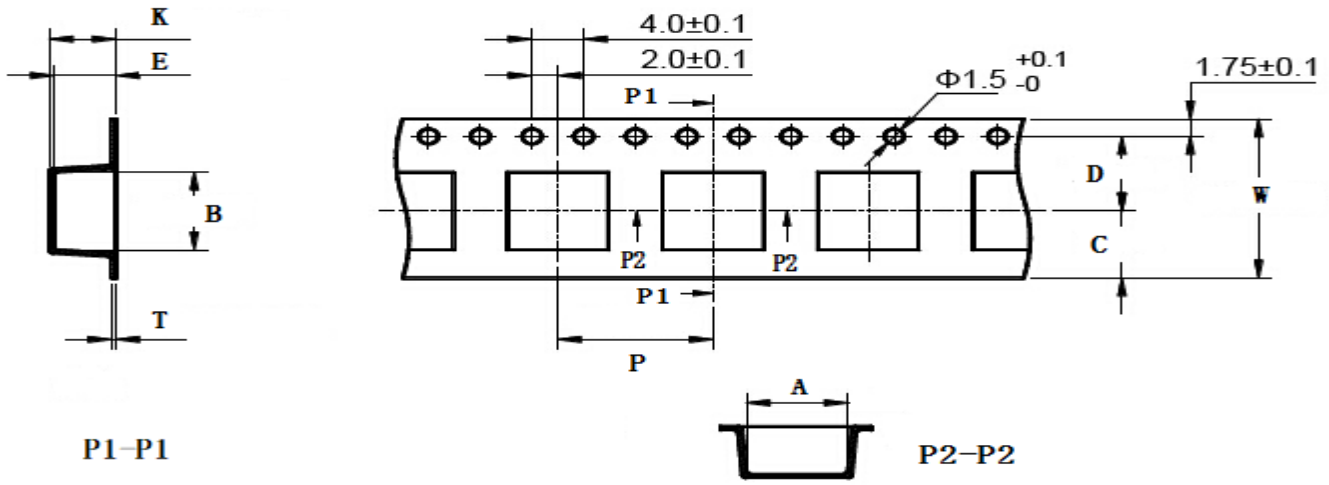
Part Number	Inductance (uH) @100KHz	DCR(mΩ)		Heat Rating Current (A)	Saturation Current (A)
		Typ.	Max.		
YSPI090840TY-100M	10±20%	45.5	51.8	8.0	10.5

※ The saturation current value is the DC current value having inductance decrease down to 30%.(at 20℃)

※ The temperature rise current value is the DC current value having temperature increase up to 40℃. (at 20℃)

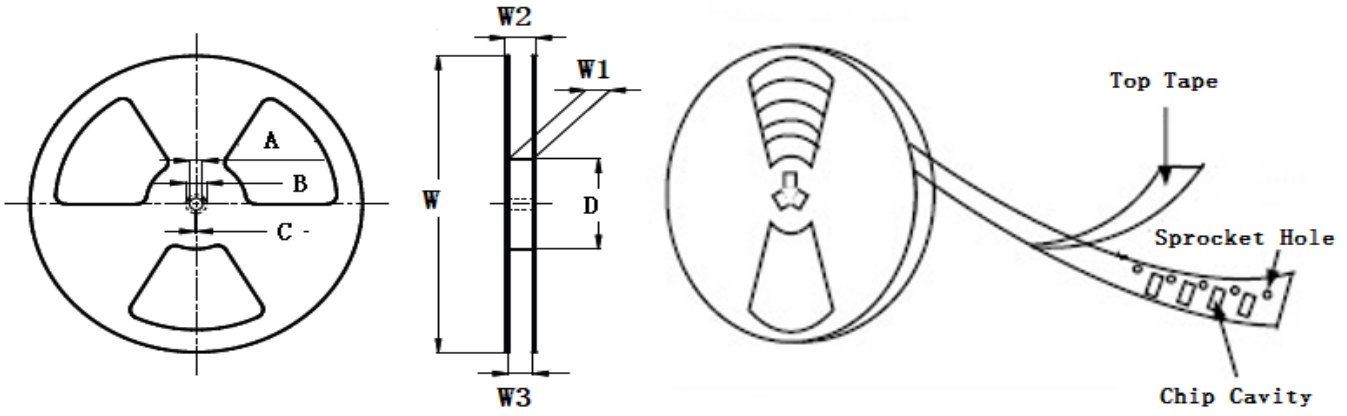
※ The rated current is the DC current value that satisfies both of current value saturation current value and temperature rise current value.

■ Taping Dimensions(Unit:mm)



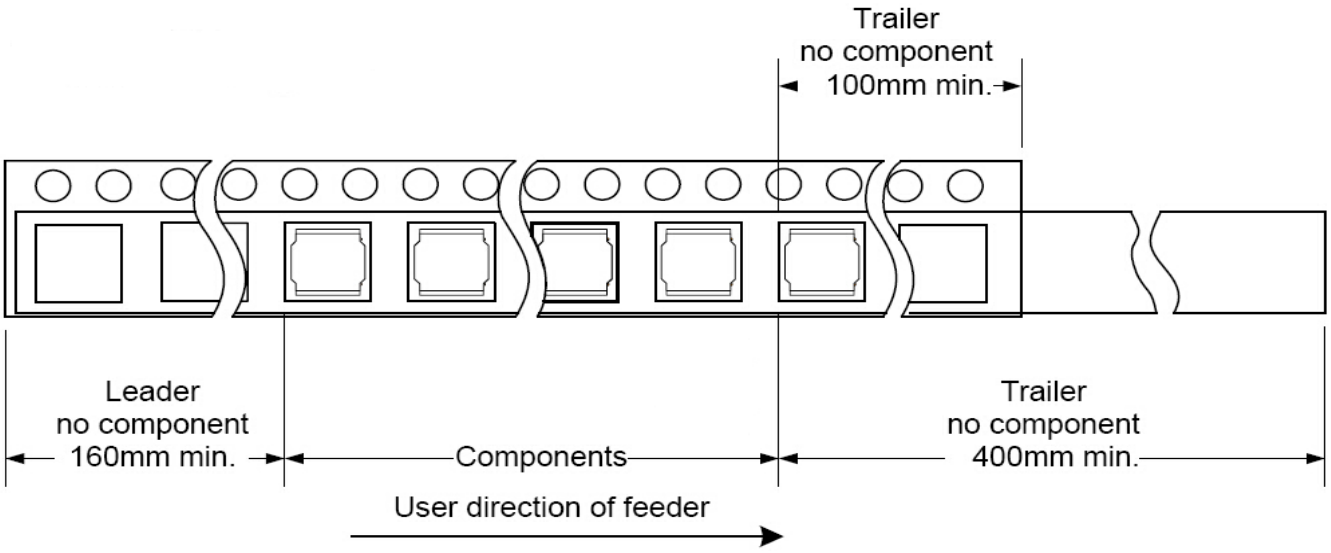
TYPE	W	A	B	C	D	E	P	K Ref	T	MPQ
YSPI090840	24±0.3	8.5±0.1	10.2±0.1	6.75	7.5±0.1	5.5±0.1	16.0±0.1	5.7	0.35±0.1	1000

■ Reel Dimensions(Unit:mm)

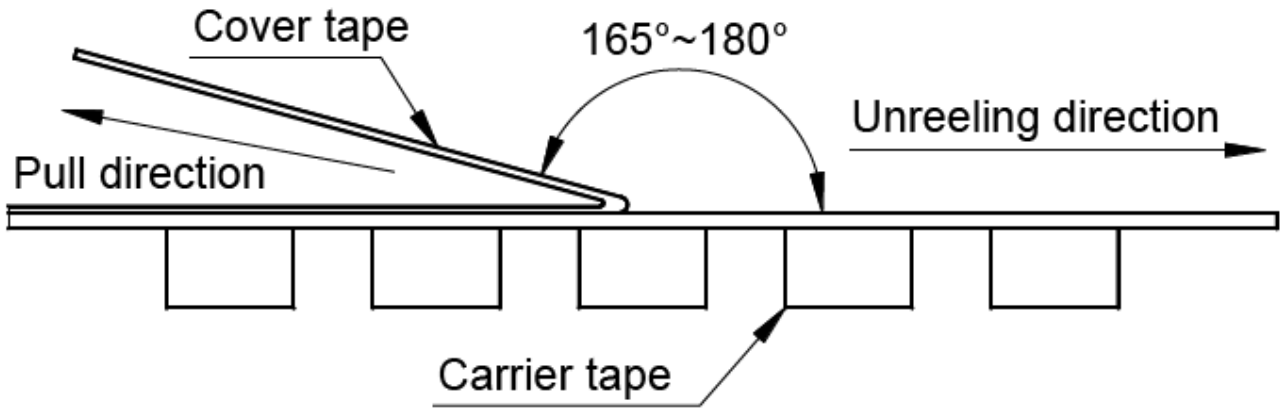


TYPE	W	W1	W2	W3	A	B	C	D
YSPI090840	330±2.0	16.4±2.0	22.4MAX	15.9 Min	13.0±0.50	21.0±0.80	2.0±0.50	100 Min

■ Direction of rolling



■ Cover tape peel off condition



Cover tape peel force shall be 0.1N to 1.3N.

Reference peel speed 300±10mm/min.